

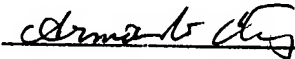
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
)
Takayama et al.)
)
Serial No.:)
)
Filed: Herewith)
)
For: Wiring Material, Semiconductor Device)
Provided With A Wiring Using The Wiring)
Material And Method of Manufacturing)
Thereof)
)
Examiner:)
)
Art Unit:)

"Express Mail" Mailing Label No. EV 321710936
Date of Deposit September 26, 2003

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Signature 

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT A

Prior to examination and calculation of fees, please amend the above-identified application as follows: